V29LC51002
2 MEGABIT (262,144 x 8 BIT)
5 VOLT CMOS FLASH MEMORY

PRELIMINARY

Features

- 256Kx8-bit Organization
- Address Access Time: 90 ns
- Single 5V ± 10% Power Supply
- Sector Erase Mode Operation
- 512 bytes per Sector, 512 Sectors
  - Sector-Erase Cycle Time: 10ms (Max)
  - Byte-Write Cycle Time: 30µs (Max)
- Minimum 1,000 Erase-Program Cycles
- Low power dissipation
  - Active Read Current: 20mA (Typ)
  - Active Program Current: 30mA (Typ)
  - Standby Current: 100µA (Max)
- Low V_{CC} Program Inhibit Below 3.5V
- CMOS and TTL Interface
- Packages:
  - 32-pin Plastic DIP
  - 32-pin PLCC

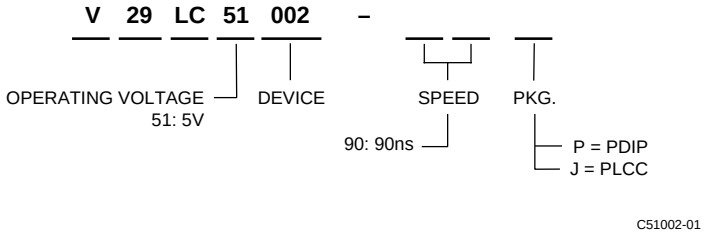
Description

The V29LC51002 is a high speed 262,144 x 8 bit CMOS flash memory. Writing or erasing the device is done with a single 5 Volt power supply. The device has separate chip enable $\overline{CE}$, write enable $\overline{WE}$, and output enable $\overline{OE}$ controls to eliminate bus contention.

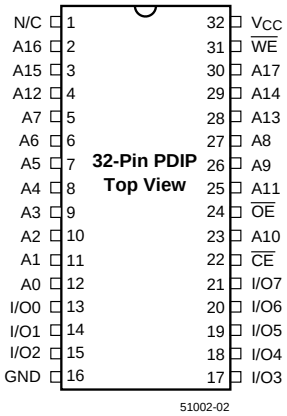
The V29LC51002 features a sector erase operation which allows each sector to be erased and reprogrammed without affecting data stored in other sectors. The device also supports full chip erase.

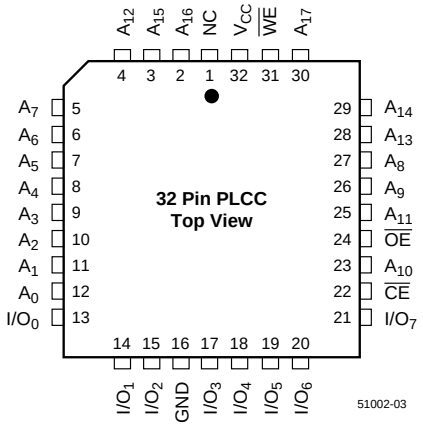
Device Usage Chart

Operating Temperature Range	Package Outline		Access Time (ns)	Temperature Mark
	P	J	90	
0°C to 70°C	•	•	•	Blank



Pin Configurations

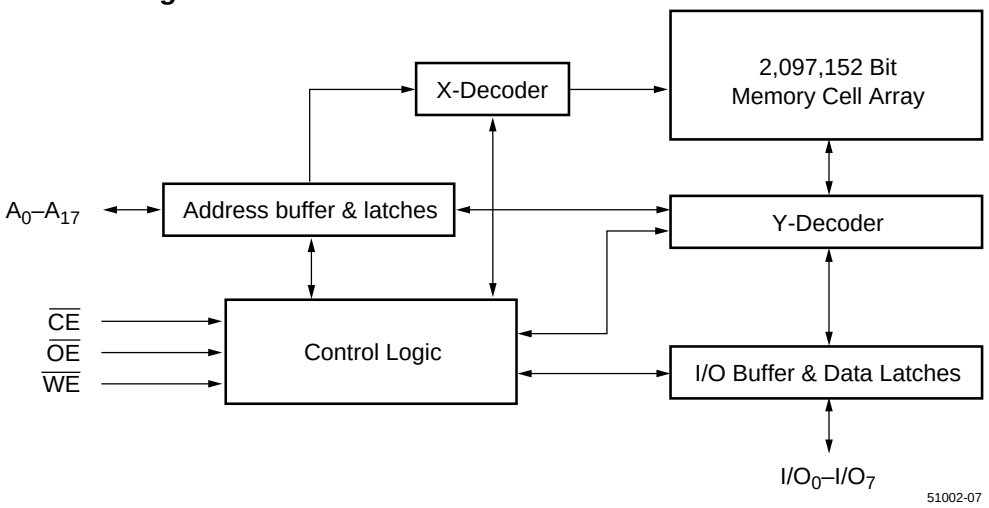




Pin Names

A_0–A_{17}	Address Inputs
I/O_0–I/O_7	Data Input/Output
$\overline{CE}$	Chip Enable
$\overline{OE}$	Output Enable
$\overline{WE}$	Write Enable
V_{CC}	5V ± 10% Power Supply
GND	Ground
NC	No Connect

Functional Block Diagram



Capacitance (1,2)

Symbol	Parameter	Test Setup	Typ.	Max.	Units
C_{IN}	Input Capacitance	V_{IN} = 0	6	8	pF
C_{OUT}	Output Capacitance	V_{OUT} = 0	8	12	pF
C_{IN2}	Control Pin Capacitance	V_{IN} = 0	8	10	pF

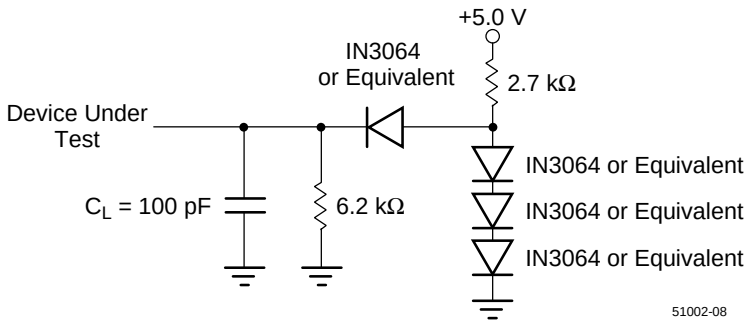
NOTE:
1. Capacitance is sampled and not 100% tested.
2. T_A = 25°C, V_{CC} = 5V ± 10%, f = 1 MHz.

Latch Up Characteristics(1)

Parameter	Min.	Max.	Unit
Input Voltage with Respect to GND on A_9, $\overline{OE}$	-1	+13	V
Input Voltage with Respect to GND on I/O, address or control pins	-1	V_{CC} + 1	V
V_{CC} Current	-100	+100	mA

NOTE:
1. Includes all pins except V_{CC}. Test conditions: V_{CC} = 5V, one pin at a time.

AC Test Load



Absolute Maximum Ratings[1]

Symbol	Parameter	Commercial	Unit
V_{IN}	Input Voltage (input or I/O pins)	-2 to +7	V
V_{IN}	Input Voltage (A_9 pin, $\overline{OE}$)	-2 to +13	V
V_{CC}	Power Supply Voltage	-0.5 to +5.5	V
T_{STG}	Storage Temerpature (Plastic)	-65 to +125	°C
T_{OPR}	Operating Temperature	0 to +70	°C
I_{OUT}	Short Circuit Current[2]	200 (Max.)	mA

NOTE:
1. Stress greater than those listed unders “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.
2. No more than one output maybe shorted at a time and not exceeding one second long.

DC Electrical Characteristics

(over the commercial operating range)

Parameter Name	Parameter	Test Conditions	Min.	Max.	Unit
V_{IL}	Input LOW Voltage	$V_{CC} = V_{CC}$ Min.	—	0.8	V
V_{IH}	Input HIGH Voltage	$V_{CC} = V_{CC}$ Max.	2	—	V
I_{IL}	Input Leakage Current	V_{IN} = GND to V_{CC}, $V_{CC} = V_{CC}$ Max.	—	±1	µA
I_{OL}	Output Leakage Current	V_{OUT} = GND to V_{CC}, $V_{CC} = V_{CC}$ Max.	—	±10	µA
V_{OL}	Output LOW Voltage	$V_{CC} = V_{CC}$ Min., I_{OL} = 2.1mA	—	0.4	V
V_{OH}	Output HIGH Voltage	$V_{CC} = V_{CC}$ Min, I_{OH} = -400µA	2.4	—	V
I_{CC1}	Read Current	$\overline{CE} = \overline{OE} = V_{IL}$, $\overline{WE} = V_{IH}$, all I/Os open, Address input = V_{IL}/V_{IH}, at f = $1/t_{RC}$ Min., $V_{CC} = V_{CC}$ Max.	—	40	mA
I_{CC2}	Write Current	$\overline{CE} = \overline{WE}$ = VIL, $\overline{OE} = V_{IH}$, $V_{CC} = V_{CC}$ Max.	—	50	mA
I_{SB}	TTL Standby Current	$\overline{CE} = \overline{OE} = \overline{WE} = V_{IH}$, $V_{CC} = V_{CC}$ Max.	—	2	mA
I_{SB1}	CMOS Standby Current	$\overline{CE} = \overline{OE} = \overline{WE} = V_{CC} - 0.3V$, $V_{CC} = V_{CC}$ Max.	—	100	µA
V_H	Device ID Voltage for A_9	$\overline{CE} = \overline{OE} = V_{IL}$, $\overline{WE} = V_{IH}$	11.5	12.5	V
I_H	Device ID Current for A_9	$\overline{CE} = \overline{OE} = V_{IL}$, $\overline{WE} = V_{IH}$, A9 = V_H Max.	—	50	µA

AC Electrical Characteristics

(over all temperature ranges)

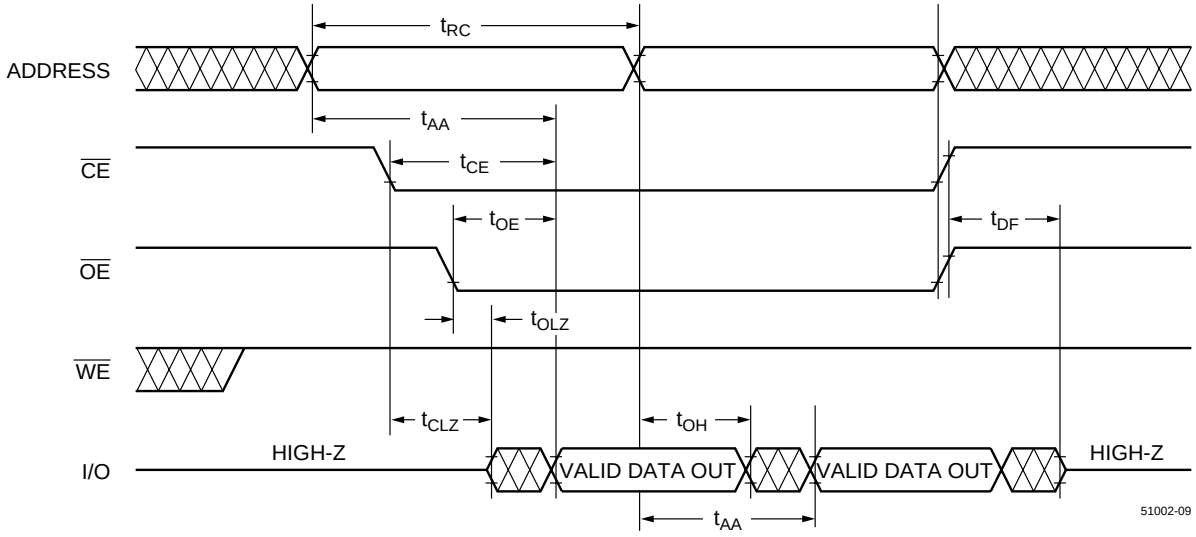
Read Cycle

Parameter Name	Parameter	-90		Unit
		Min.	Max.	
t_{RC}	Read Cycle Time	90	—	ns
t_{AA}	Address Access Time	—	90	ns
t_{ACS}	Chip Enable Access Time	—	90	ns
t_{OE}	Output Enable Access Time	—	45	ns
t_{CLZ}	$\overline{CE}$ Low to Output Active	0	—	ns
t_{OLZ}	$\overline{OE}$ Low to Output Active	0	—	ns
t_{DF}	$\overline{OE}$ or $\overline{CE}$ High to Output in High Z	0	40	ns
t_{OH}	Output Hold from Address Change	0	—	ns

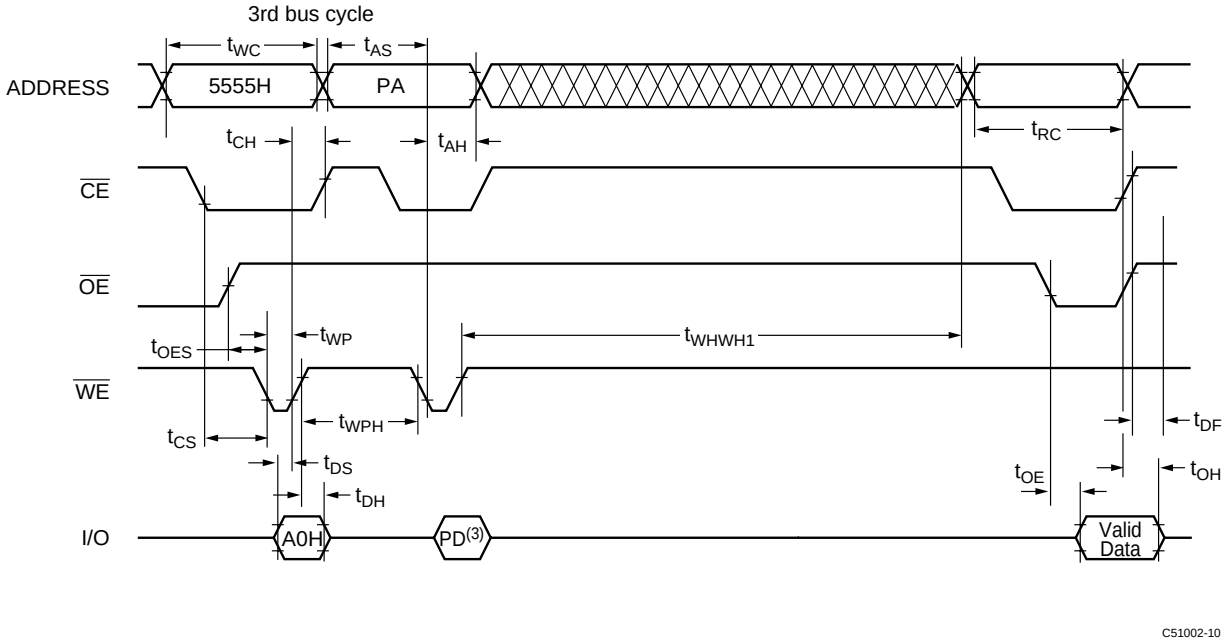
Program (Erase/Program) Cycle

Parameter Name	Parameter	-90			Unit
		Min.	Typ.	Max.	
t_{WC}	Write Cycle Time	90	—	—	ns
t_{AS}	Address Setup Time	0	—	—	ns
t_{AH}	Address Hold Time	45	—	—	ns
t_{CS}	$\overline{CE}$ Setup Time	0	—	—	ns
t_{CH}	$\overline{CE}$ Hold Time	0	—	—	ns
t_{OES}	$\overline{OE}$ Setup Time	0	—	—	ns
t_{OEH}	$\overline{OE}$ High Hold Time	0	—	—	ns
t_{WP}	$\overline{WE}$ Pulse Width	45	—	—	ns
t_{WPH}	$\overline{WE}$ Pulse Width High	30	—	—	ns
t_{DS}	Data Setup Time	30	—	—	ns
t_{DH}	Data Hold Time	0	—	—	ns
t_{WHWH1}	Programming Cycle	—	—	30	µs
t_{WHWH2}	Sector Erase Cycle	—	—	10	ms
t_{WHWH3}	Chip Erase Cycle	—	3	—	sec

Waveforms of Read Cycle

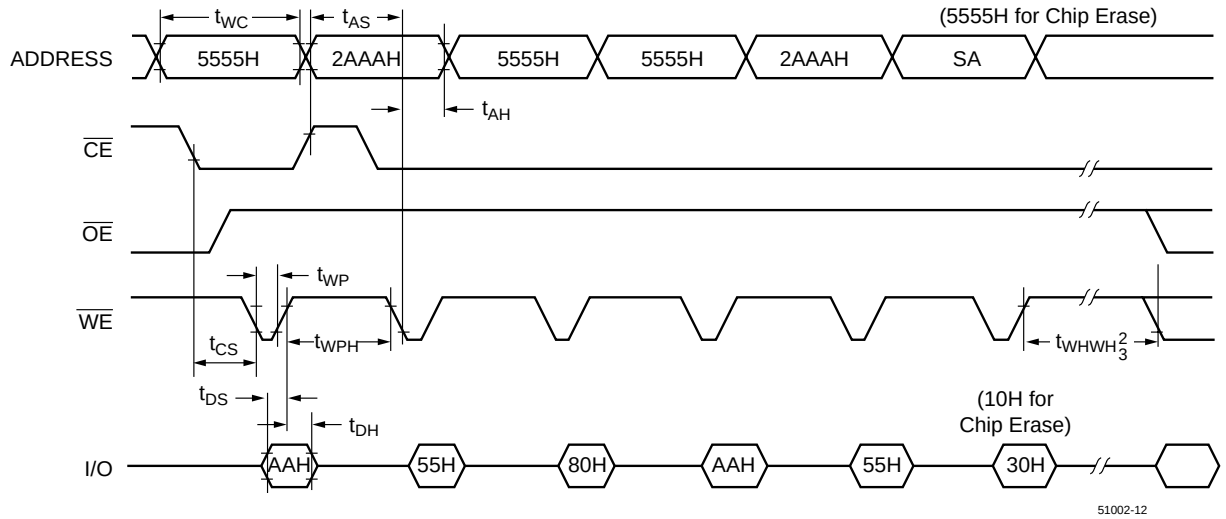


Waveforms of $\overline{WE}$ Controlled-Program Cycle



NOTES:
1. PA: The address of the memory location to be programmed.
2. PD: The data at the byte address to be programmed.

Waveforms of Erase Cycle(1)



NOTES:
1. PA: The address of the memory location to be programmed.
2. PD: The data at the byte address to be programmed.
3. SA: The sector address for Sector Erase.

FUNCTIONAL DESCRIPTION

Read Cycle

A read cycle is performed by holding both $\overline{CE}$ and $\overline{OE}$ signals LOW. Data Out becomes valid only when these conditions are met. During a read cycle $\overline{WE}$ must be HIGH prior to $\overline{CE}$ and $\overline{OE}$ going LOW. $\overline{WE}$ must remain HIGH during the read operation for the read to complete (see Table 1).

Output Disable

Returning $\overline{OE}$ or $\overline{CE}$ HIGH, whichever occurs first will terminate the read operation and place the I/O pins in the HIGH-Z state.

Standby

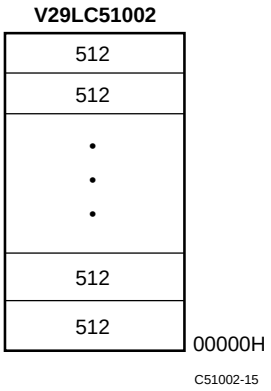
The device will enter standby mode when the $\overline{CE}$ signal is HIGH. The I/O pins are placed in the HIGH-Z, independent of the $\overline{OE}$ input state.

Command Sequence

The V29LC51002 does not provide the “reset” feature to return the chip to its normal state when an incomplete command sequence or an interruption has happened. In this case, normal operation (Read Mode) can be restored by issuing a “non-existent” command sequence, for example Address: 5555H, Data FFH.

Byte Write Cycle

The V29LC51002 is programmed on a byte-by-byte basis. The byte write operation is initiated by using a specific four-bus-cycle sequence: two unlock program cycles, a program setup command and program data program cycles (see Table 2).



During the byte write cycle, addresses are latched on the falling edge of either $\overline{CE}$ or $\overline{WE}$, whichever is last. Data is latched on the rising edge of $\overline{CE}$ or $\overline{WE}$, whichever is first. The byte write cycle can be $\overline{CE}$ controlled or $\overline{WE}$ controlled.

Sector Erase Cycle

The V29LC51002 features a sector erase operation which allows each sector to be erased and reprogrammed without affecting data stored in other sectors. Sector erase operation is initiated by using a specific six-bus-cycle sequence: Two unlock program cycles, a setup command, two additional unlock program cycles, and the sector erase command (see Table 2). A sector must be first erased before it can be re-written. While in the internal erase mode, the device ignores any program attempt into the device. Sector erase is completed in 10ms max. The V29LC51002 is shipped fully erased (all bits = 1).

Table 1. Operation Modes Decoding

Decoding Mode	$\overline{CE}$	$\overline{OE}$	$\overline{WE}$	A_0	A_1	A_9	I/O
Read	V_{IL}	V_{IL}	V_{IH}	A_0	A_1	A_9	READ
Byte Write	V_{IL}	V_{IH}	V_{IL}	A_0	A_1	A_9	PD
Standby	V_{IH}	X	X	X	X	X	HIGH-Z
Output Disable	V_{IL}	V_{IH}	V_{IH}	X	X	X	HIGH-Z

NOTES:

1. X = Don’t Care, V_{IH} = HIGH, V_{IL} = LOW, V_H = 12.5V Max.
2. PD: The data at the byte address to be programmed.

Table 2. Command Codes

Command Sequence	First Bus Program Cycle		Second Bus Program Cycle		Third Bus Program Cycle		Fourth Bus Program Cycle		Fifth Bus Program Cycle		Six Bus Program Cycle	
	Address	Data	Address	Data	Address	Data	Address	Data	Address	Data	Address	Data
Read	XXXXH	F0H										
Read	5555H	AAH	2AAAH	55H	5555H	F0H	RA(1)	RD(2)				
Autoselect	5555H	AAH	2AAAH	55H	5555H	90H	00H	40H(6)				
							01H	82H(7)				
Byte Program	5555H	AAH	2AAAH	55H	5555H	A0H	PA	PD(4)				
Chip Erase	5555H	AAH	2AAAH	55H	5555H	80H	5555H	AAH	2AAAH	55H	5555H	10H
Sector Erase	5555H	AAH	2AAAH	55H	5555H	80H	5555H	AAH	2AAAH	55H	SA(5)	30H

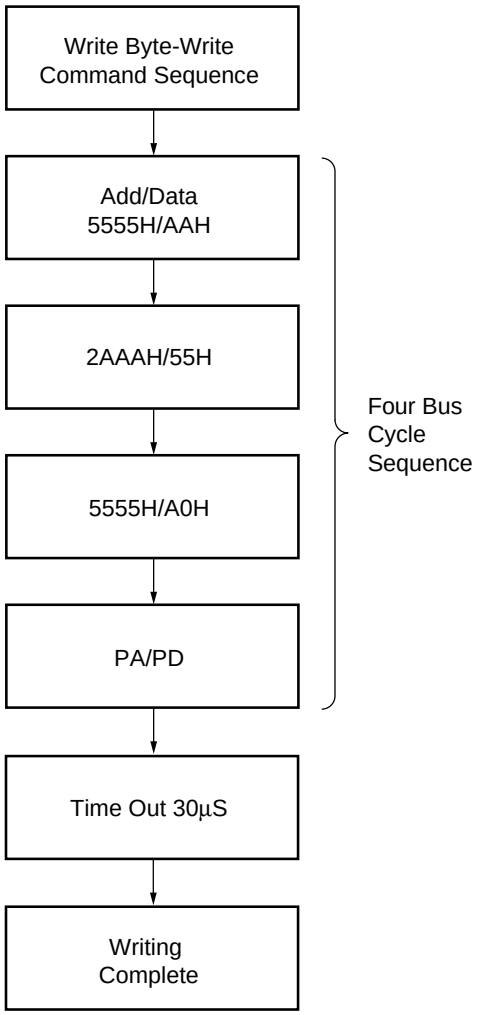
NOTES:
1. RA: Read Address
2. RD: Read Data
3. PA: The address of the memory location to be programmed.
4. PD: The data at the byte address to be programmed.
5. SA(5): Sector Address
6. 40H: Manufacturing ID
7. 82H: Device ID

Chip Erase Cycle

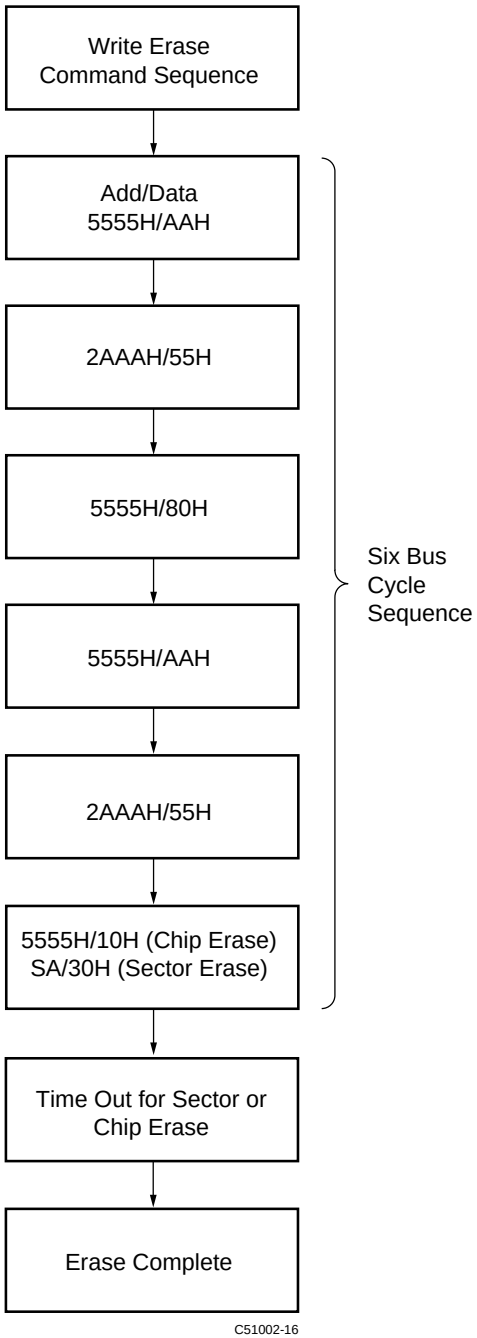
The V29LC51002 features a chip-erase operation. The chip erase operation is initiated by using a specific six-bus-cycle sequence: two unlock program cycles, a setup command, two additional unlock program cycles, and the chip erase command (see Table 2).

The automatic erase begins on the rising edge of the last $\overline{WE}$ or $\overline{CE}$ pulse in the command sequence and is completed in 3 sec max.

Byte Program Algorithm



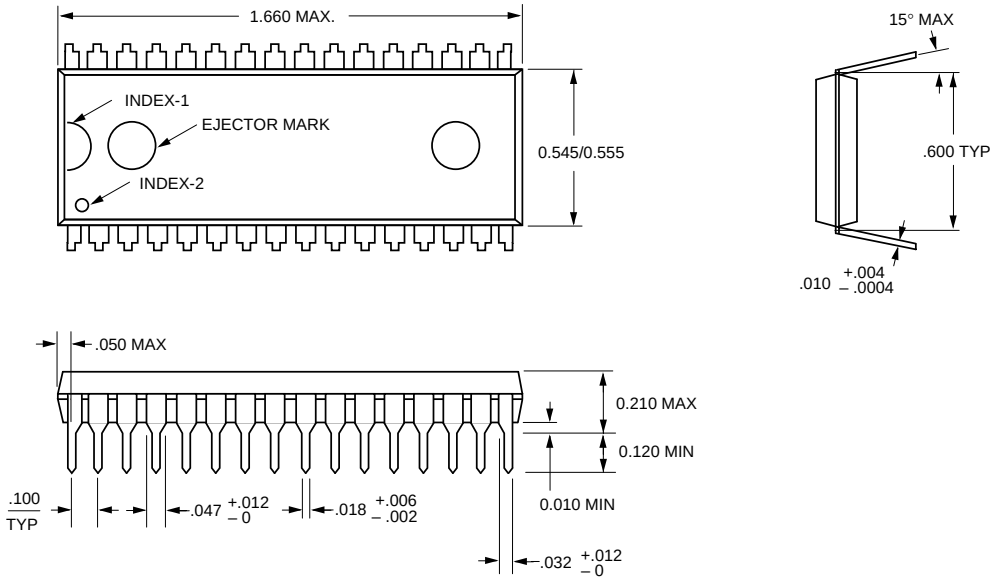
Chip/Sector Erase Algorithm



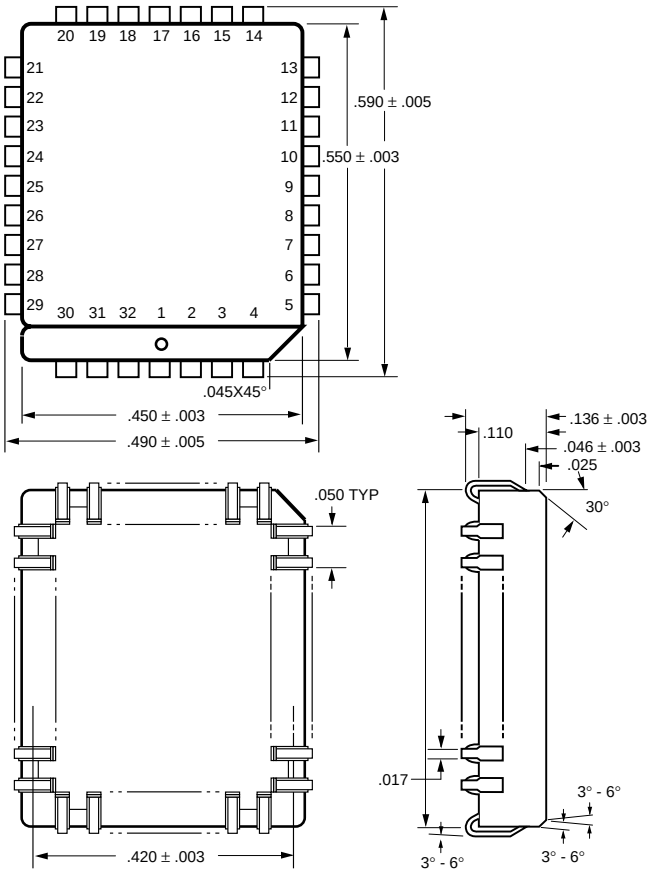
C51002-16

Package Diagrams

32-pin Plastic DIP



32-pin PLCC



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